



In re Applicant:

Brad D. Rumsey

Art Unit:

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2841

Serial No.:

09/377,286

999999

Filed:

August 18, 1999

Examiner:

K. Cuneo

Jitle:

Positioning Flowable

Solder For Bonding **Integrated Circuit**

Docket No. §

MICT-0050-US

(99-0325)

Elements

Commissioner for Patents Washington, D.C. 20231

REPLY TO PAPER NO. 7

Sir:

This paper is submitted in response to the final Office Action dated July 6, 2001 for which the shortened-statutory period for response is set to expire on October 6, 2001.

REMARKS

The Examiner maintained his rejection of all claims being considered as being anticipated by Healy et al. Specifically, the claims were rejected as being anticipated by either Figure 1 or 2 of Healy et al., or as being an inherent function of Healy et al.'s structure.

Independent claim 1 includes a trace and a trace stub that are coupled to a bond pad, each extending away from the bond pad in a different direction. The trace applies an attractive force to solder placed on the bond pad and the trace stub applies a counteractive attractive force to the solder. Likewise,

> Date of Deposit: I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner-for Patents, Washington, DC 20231.

Sharon V. Hart